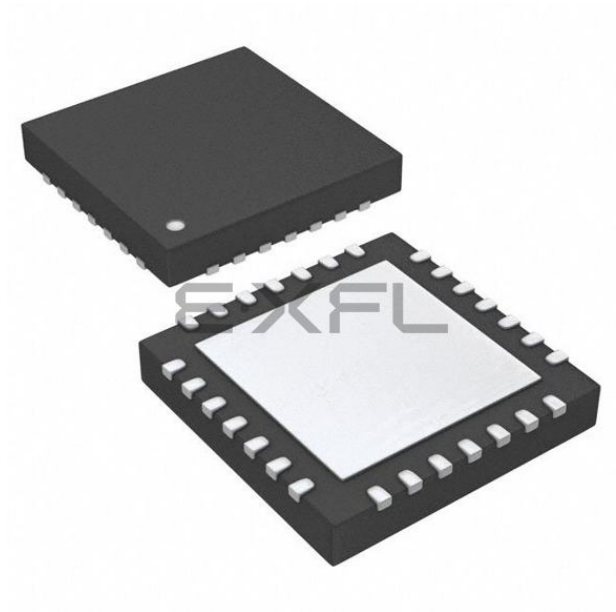

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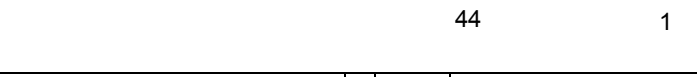
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	19
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx250f128b-v-ml

TABLE 9: PIN NAMES FOR 44-PIN GENERAL PURPOSE DEVICES

44-PIN QFN (TOP VIEW)(1,2,3,5)

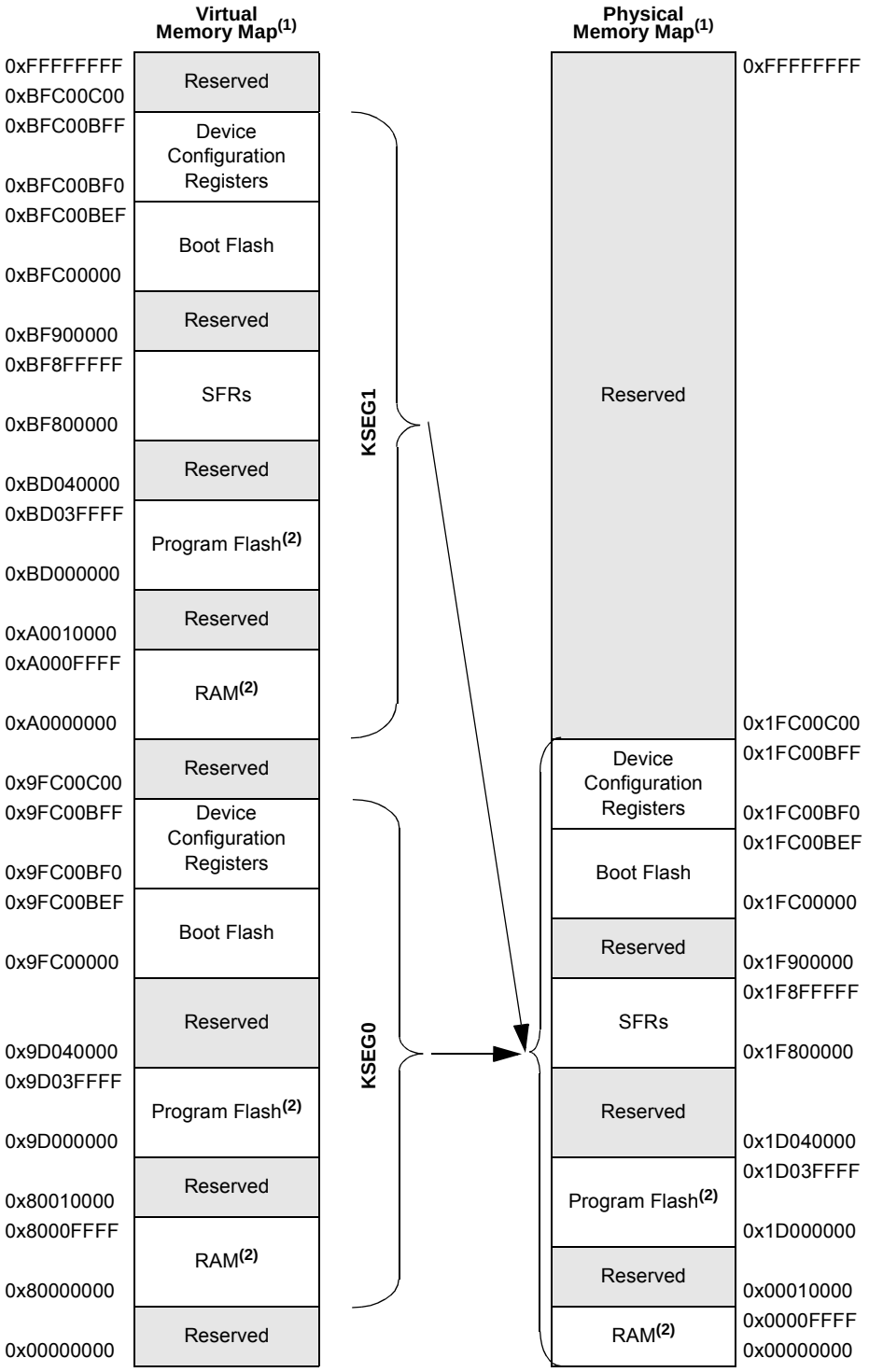
PIC32MX110F016D
PIC32MX120F032D
PIC32MX130F064D
PIC32MX130F256D
PIC32MX150F128D
PIC32MX170F256D



Pin #	Full Pin Name	Pin #	Full Pin Name
1	RPB9/SDA1/CTED4/PMD3/RB9	23	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2
2	RPC6/PMA1/RC6	24	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3
3	RPC7/PMA0/RC7	25	AN6/RPC0/RC0
4	RPC8/PMA5/RC8	26	AN7/RPC1/RC1
5	RPC9/CTED7/PMA6/RC9	27	AN8/RPC2/PMA2/RC2
6	VSS	28	VDD
7	VCAP	29	VSS
8	PGED2/RPB10/CTED11/PMD2/RB10	30	OSC1/CLKI/RPA2/RA2
9	PGEC2/RPB11/PMD1/RB11	31	OSC2/CLKO/RPA3/RA3
10	AN12/PMD0/RB12	32	TDO/RPA8/PMA8/RA8
11	AN11/RPB13/CTPLS/PMRD/RB13	33	SOSCI/RPB4/RB4
12	PGED4(4)/TMS/PMA10/RA10	34	SOSCO/RPA4/T1CK/CTED9/RA4
13	PGEC4(4)/TCK/CTED8/PMA7/RA7	35	TDI/RPA9/PMA9/RA9
14	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14	36	RPC3/RC3
15	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15	37	RPC4/PMA4/RC4
16	AVSS	38	RPC5/PMA3/RC5
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0	41	PGED3/RPB5/PMD7/RB5
20	VREF-/CVREF-/AN1/RPA1/CTED2/RA1	42	PGEC3/RPB6/PMD6/RB6
21	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0	43	RPB7/CTED3/PMD5/INT0/RB7
22	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1	44	RPB8/SCL1/CTED10/PMD4/RB8

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.
2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.
3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
4: This pin function is not available on PIC32MX110F016D and PIC32MX120F032D devices.
5: Shaded pins are 5V tolerant.

FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

5.0 FLASH PROGRAM MEMORY

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Program Memory"** (DS60001121), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family devices contain an internal Flash program memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self-Programming (RTSP)
- EJTAG Programming
- In-Circuit Serial Programming™ (ICSP™)

RTSP is performed by software executing from either Flash or RAM memory. Information about RTSP techniques is available in **Section 5. "Flash Program Memory"** (DS60001121) in the *"PIC32 Family Reference Manual".*

EJTAG is performed using the EJTAG port of the device and an EJTAG capable programmer.

ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP.

The EJTAG and ICSP methods are described in the "*PIC32 Flash Programming Specification*" (DS60001145), which can be downloaded from the Microchip web site.

Note: The Flash page size on PIC32MX-1XX/2XX 28/36/44-pin Family devices is 1 KB and the row size is 128 bytes (256 IW and 32 IW, respectively).

REGISTER 5-4: NVMDATA: FLASH PROGRAM DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMDATA<31:0>:** Flash Programming Data bits

Note: The bits in this register are only reset by a Power-on Reset (POR).

REGISTER 5-5: NVMSRCADDR: SOURCE DATA ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMSRCADDR<31:0>:** Source Data Address bits

The system physical address of the data to be programmed into the Flash when the NVMOP<3:0> bits (NVMCON<3:0>) are set to perform row programming.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-y	R/W-y	R/W-y	R/W-0	R/W-0	R/W-1
	—	—	PLLODIV<2:0>			FRCDIV<2:0>		
23:16	U-0	R-0	R-1	R/W-y	R/W-y	R/W-y	R/W-y	R/W-y
	—	SOSCRDY	PBDIVRDY	PBDIV<1:0>		PLLMULT<2:0>		
15:8	U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
	—	COSC<2:0>			—	NOSC<2:0>		
7:0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-y	R/W-0
	CLKLOCK	ULOCK(1)	SLOCK	SLPEN	CF	UFRCEN(1)	SOSCEN	OSWEN

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29-27 **PLLODIV<2:0>:** Output Divider for PLL
- 111 = PLL output divided by 256
- 110 = PLL output divided by 64
- 101 = PLL output divided by 32
- 100 = PLL output divided by 16
- 011 = PLL output divided by 8
- 010 = PLL output divided by 4
- 001 = PLL output divided by 2
- 000 = PLL output divided by 1

bit 26-24 **FRCDIV<2:0>:** Internal Fast RC (FRC) Oscillator Clock Divider bits
- 111 = FRC divided by 256
- 110 = FRC divided by 64
- 101 = FRC divided by 32
- 100 = FRC divided by 16
- 011 = FRC divided by 8
- 010 = FRC divided by 4
- 001 = FRC divided by 2 (default setting)
- 000 = FRC divided by 1

bit 23 **Unimplemented:** Read as '0'

bit 22 **SOSCRDY:** Secondary Oscillator (SOSC) Ready Indicator bit
- 1 = The Secondary Oscillator is running and is stable
- 0 = The Secondary Oscillator is still warming up or is turned off

bit 21 **PBDIVRDY:** Peripheral Bus Clock (PBCLK) Divisor Ready bit
- 1 = PBDIV<1:0> bits can be written
- 0 = PBDIV<1:0> bits cannot be written

bit 20-19 **PBDIV<1:0>:** Peripheral Bus Clock (PBCLK) Divisor bits
- 11 = PBCLK is SYSCLK divided by 8 (default)
- 10 = PBCLK is SYSCLK divided by 4
- 01 = PBCLK is SYSCLK divided by 2
- 00 = PBCLK is SYSCLK divided by 1

Note 1: This bit is only available on PIC32MX2XX devices.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

9.1 DMA Control Registers

TABLE 9-1: DMA GLOBAL REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	DMACON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	SUSPEND	DMABUSY	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	DMACH<2:0>(2)			0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

TABLE 9-2: DMA CRC REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3030	DCRCCON	31:16	—	—	BYTO<1:0>		WBO	—	—	BITO	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	PLEN<4:0>					CRCEN	CRCAPP	CRCTYP	—	—	CRCCH<2:0>			0000
3040	DCRCDATA	31:16	DCRCDATA<31:0>																0000
		15:0																	0000
3050	DCRCXOR	31:16	DCRCXOR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

11.0 I/O PORTS

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "I/O Ports"** (DS60001120), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

General purpose I/O pins are the simplest of peripherals. They allow the PIC® MCU to monitor and control other devices. To add flexibility and functionality, some pins are multiplexed with alternate functions.

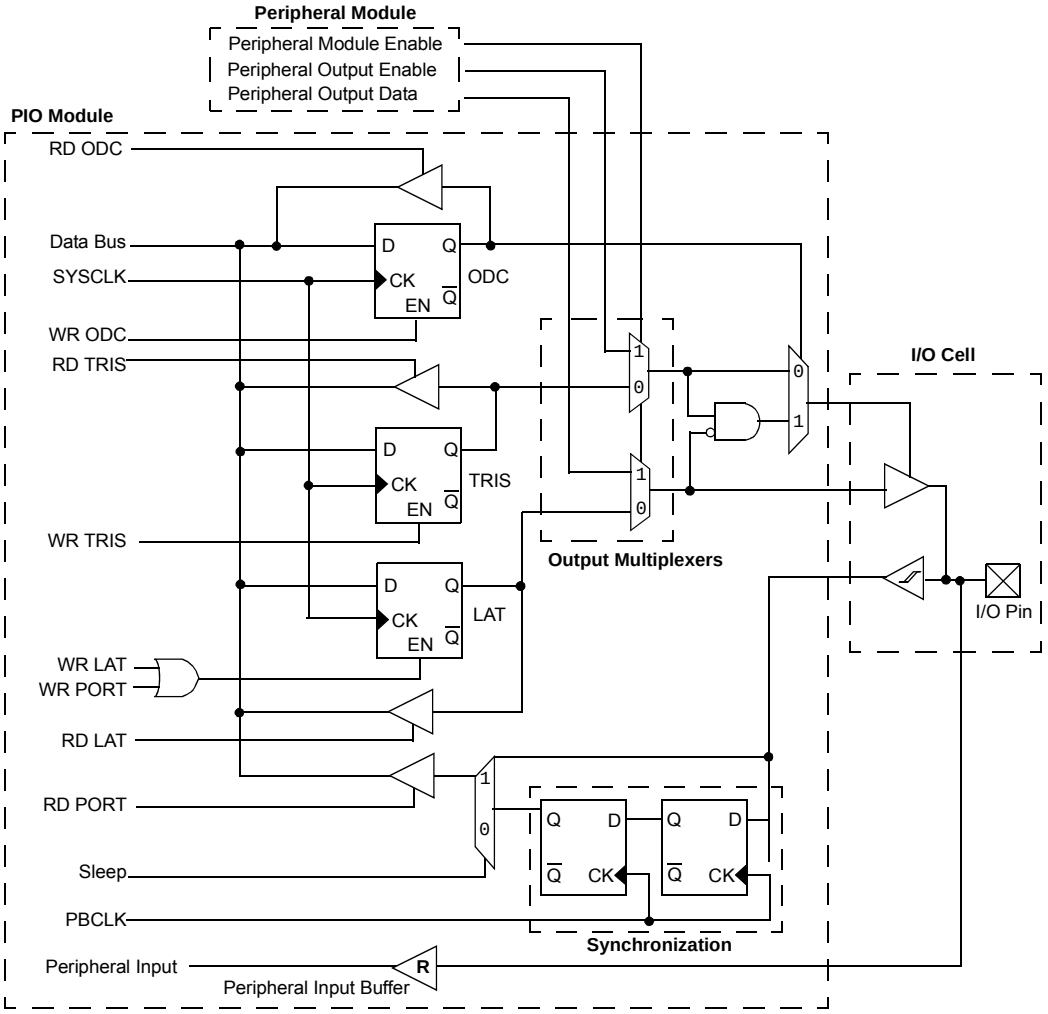
These functions depend on which peripheral features are on the device. In general, when a peripheral is functioning, that pin may not be used as a general purpose I/O pin.

Key features of this module include:

- Individual output pin open-drain enable/disable
- Individual input pin weak pull-up and pull-down
- Monitor selective inputs and generate interrupt when change in pin state is detected
- Operation during Sleep and Idle modes
- Fast bit manipulation using CLR, SET, and INV registers

Figure 11-1 illustrates a block diagram of a typical multiplexed I/O port.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL MULTIPLEXED PORT STRUCTURE



Legend: R = Peripheral input buffer types may vary. Refer to Table 1-1 for peripheral details.

Note: This block diagram is a general representation of a shared port/peripheral structure and is only provided for illustration purposes. The actual structure for any specific port/peripheral combination may be different than it is shown here.

REGISTER 22-3: AD1CON3: ADC CONTROL REGISTER 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADRC	—	—	SAMC<4:0>(1)				
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W	R/W-0
	ADCS<7:0>(2)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ADRC:** ADC Conversion Clock Source bit
1 = Clock derived from FRC
0 = Clock derived from Peripheral Bus Clock (PBCLK)

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD (Not allowed)

bit 7-0 **ADCS<7:0>:** ADC Conversion Clock Select bits(2)
11111111 = TPB • 2 • (ADCS<7:0> + 1) = 512 • TPB = TAD
•
•
•
00000001 = TPB • 2 • (ADCS<7:0> + 1) = 4 • TPB = TAD
00000000 = TPB • 2 • (ADCS<7:0> + 1) = 2 • TPB = TAD

Note 1: This bit is only used if the SSRC<2:0> bits (AD1CON1<7:5>) = 111.
2: This bit is not used if the ADRC (AD1CON3<15>) bit = 1.

REGISTER 24-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ON(1)	—	—	—	—	—	—	—
7:0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	CVROE	CVRR	CVRSS	CVR<3:0>			

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator Voltage Reference On bit(1)
- 1 = Module is enabled
  Setting this bit does not affect other bits in the register.
- 0 = Module is disabled and does not consume current.
  Clearing this bit does not affect the other bits in the register.

bit 14-7 **Unimplemented:** Read as '0'

bit 6 **CVROE:** CVREFOUT Enable bit
- 1 = Voltage level is output on CVREFOUT pin
- 0 = Voltage level is disconnected from CVREFOUT pin

bit 5 **CVRR:** CVREF Range Selection bit
- 1 = 0 to 0.67 CVRSRC, with CVRSRC/24 step size
- 0 = 0.25 CVRSRC to 0.75 CVRSRC, with CVRSRC/32 step size

bit 4 **CVRSS:** CVREF Source Selection bit
- 1 = Comparator voltage reference source, CVRSRC = (VREF+) – (VREF-)
- 0 = Comparator voltage reference source, CVRSRC = AVDD – AVSS

bit 3-0 **CVR<3:0>:** CVREF Value Selection 0 ≤ CVR<3:0> ≤ 15 bits

When CVRR = 1:
CVREF = (CVR<3:0>/24) • (CVRSRC)

When CVRR = 0:
CVREF = 1/4 • (CVRSRC) + (CVR<3:0>/32) • (CVRSRC)

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-0	r-1	r-1	R/P	r-1	r-1	r-1	R/P
	—	—	—	CP	—	—	—	BWP
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	PWP<8:6>(3)		
15:8	R/P	R/P	R/P	R/P	R/P	R/P	r-1	r-1
	PWP<5:0>						—	—
7:0	r-1	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	—	—	—	ICESEL<1:0>(2)		JTAGEN(1)	DEBUG<1:0>	

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Reserved:** Write '0'

bit 30-29 **Reserved:** Write '1'

bit 28 **CP:** Code-Protect bit
Prevents boot and program Flash memory from being read or modified by an external programming device.
1 = Protection is disabled
0 = Protection is enabled

bit 27-25 **Reserved:** Write '1'

bit 24 **BWP:** Boot Flash Write-Protect bit
Prevents boot Flash memory from being modified during code execution.
1 = Boot Flash is writable
0 = Boot Flash is not writable

bit 23-19 **Reserved:** Write '1'

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the **"Pin Diagrams"** section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

REGISTER 27-5: CFGCON: CONFIGURATION CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
	—	—	IOLOCK(1)	PMDLOCK(1)	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-1	U-0	U-1	R/W-1
	—	—	—	—	JTAGEN	—	—	TDOEN

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13 **IOLOCK:** Peripheral Pin Select Lock bit(1)
- 1 = Peripheral Pin Select is locked. Writes to PPS registers is not allowed.
- 0 = Peripheral Pin Select is not locked. Writes to PPS registers is allowed.

bit 12 **PMDLOCK:** Peripheral Module Disable bit(1)
- 1 = Peripheral module is locked. Writes to PMD registers is not allowed.
- 0 = Peripheral module is not locked. Writes to PMD registers is allowed.

bit 11-4 **Unimplemented:** Read as '0'

bit 3 **JTAGEN:** JTAG Port Enable bit
- 1 = Enable the JTAG port
- 0 = Disable the JTAG port

bit 2-1 **Unimplemented:** Read as '1'

bit 0 **TDOEN:** TDO Enable for 2-Wire JTAG bit
- 1 = 2-wire JTAG protocol uses TDO
- 0 = 2-wire JTAG protocol does not use TDO

Note 1: To change this bit, the unlock sequence must be performed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

NOTES:

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage (Note 2)**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

FIGURE 30-5: EXTERNAL RESET TIMING CHARACTERISTICS

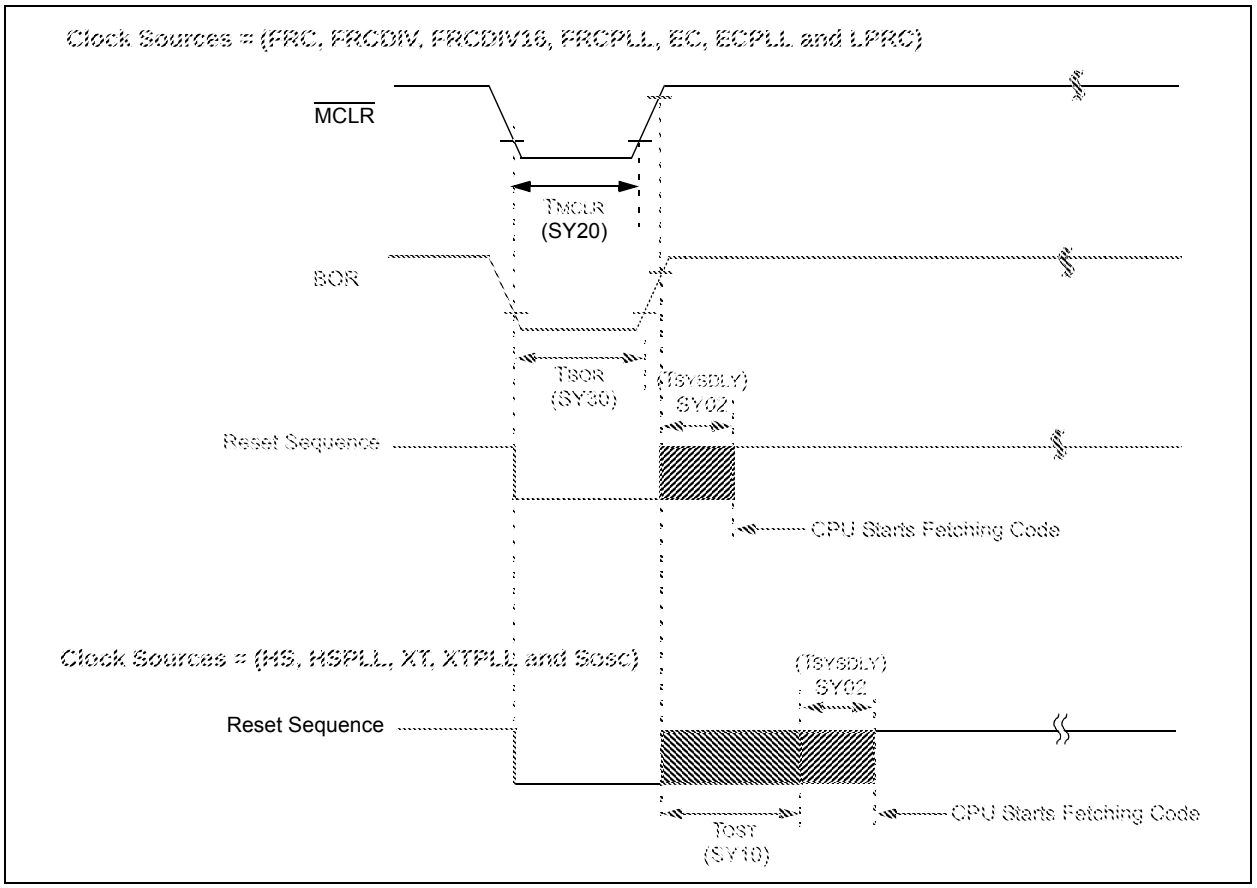


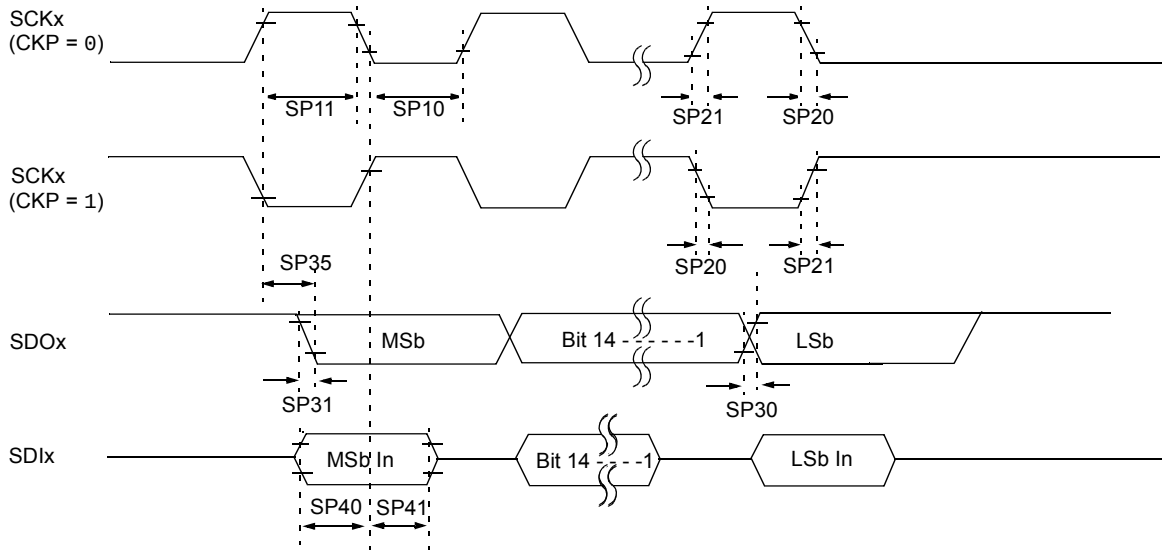
TABLE 30-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	—
SY02	TSYSDLY	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	1 μs + 8 SYSCLK cycles	—	—	—
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

FIGURE 30-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-28: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	TSCK/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	TSCK/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 30-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

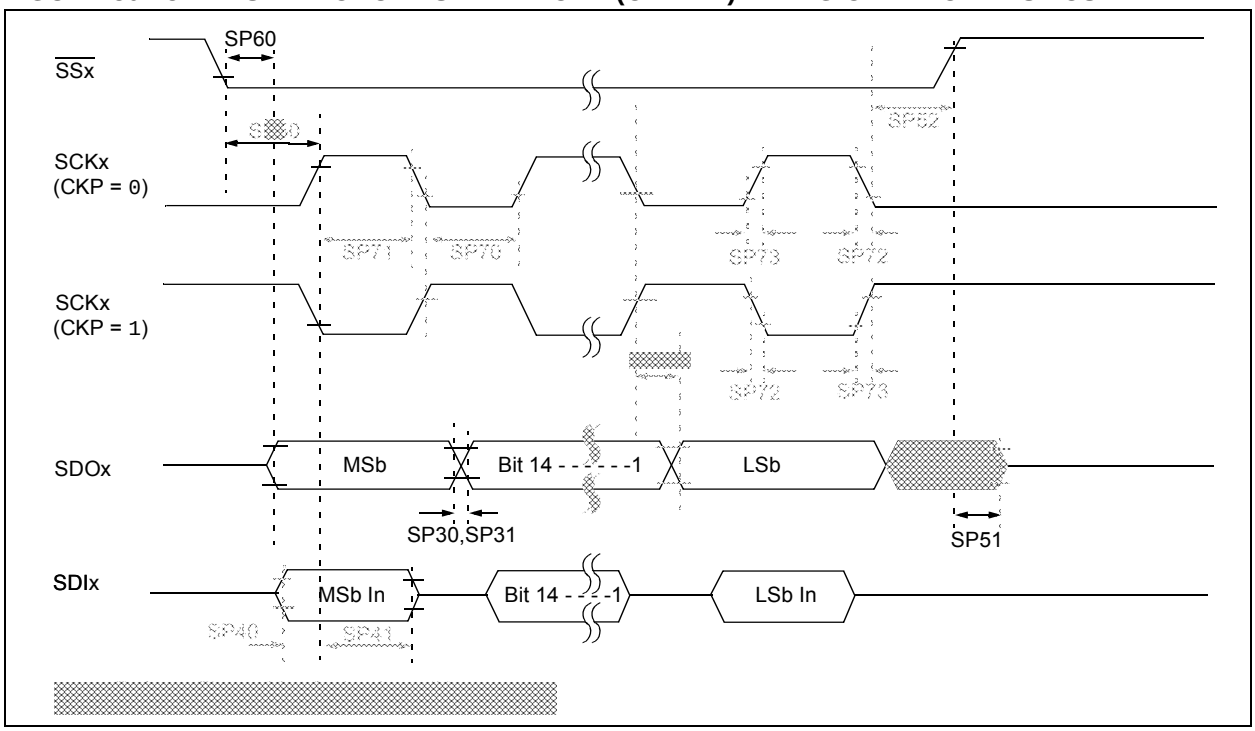


TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	5	10	ns	—
SP73	TscR	SCKx Input Rise Time	—	5	10	ns	—
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	20	ns	VDD > 2.7V
			—	—	30	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input	175	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

TABLE 30-41: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3):2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CTMU CURRENT SOURCE							
CTMUI1	IOUT1	Base Range(1)	—	0.55	—	µA	CTMUCON<9:8> = 01
CTMUI2	IOUT2	10x Range(1)	—	5.5	—	µA	CTMUCON<9:8> = 10
CTMUI3	IOUT3	100x Range(1)	—	55	—	µA	CTMUCON<9:8> = 11
CTMUI4	IOUT4	1000x Range(1)	—	550	—	µA	CTMUCON<9:8> = 00
CTMUFV1	VF	Temperature Diode Forward Voltage(1,2)	—	0.598	—	V	TA = +25ºC, CTMUCON<9:8> = 01
			—	0.658	—	V	TA = +25ºC, CTMUCON<9:8> = 10
			—	0.721	—	V	TA = +25ºC, CTMUCON<9:8> = 11
CTMUFV2	VFVR	Temperature Diode Rate of Change(1,2)	—	-1.92	—	mV/ºC	CTMUCON<9:8> = 01
			—	-1.74	—	mV/ºC	CTMUCON<9:8> = 10
			—	-1.56	—	mV/ºC	CTMUCON<9:8> = 11

Note 1: Nominal value at center point of current trim range (CTMUCON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing. Measurements taken with the following conditions:

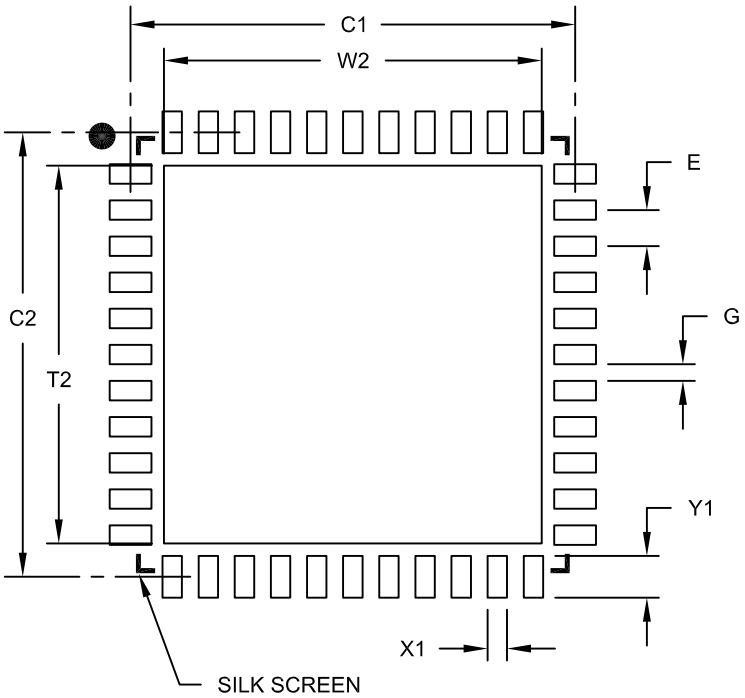
- VREF+ = AVDD = 3.3V
- ADC module configured for conversion speed of 500 ksps
- All PMD bits are cleared (PMDx = 0)
- Executing a while(1) statement
- Device operating from the FRC with no PLL

3: The CTMU module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

NOTES:

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

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